



WELCOME TO ESTC 2022

Conference Scope

Organized by IEEE-EPS (former CPMT) since 2006, the Electronics System-Integration Technology Conferences (ESTC) series is the premier event covering latest developments in packaging technology and new applications.

ESTC completes the triumvirate together with ECTC in the United States and EPTC in Singapore and thus supports the global community of electronics packaging engineers and scientists.

About Sibiu, Romania

Sibiu (German Hermannstadt) is the capital of Sibiu county in South Transylvania. It is at about 290 km north-west from Bucharest, the capital of Romania. Nicknamed »The City with Eyes«, Sibiu is a well-known tourist destination, known for its culture, history, gastronomy and diverse architecture, which includes the iconic houses with eyes.

Travel Information

Sibiu has an international airport and is easy to reach from many European cities. Please check our website at www.estc-conference.net for information on how to get there, or contact alexandru.ujupan@ctc.travel

CONTACT

Local Conference Committee

estc@estc-conference.net

General Chair

Paul M. Svasta
University Politehnica of Bucharest, Romania

Executive Chair

Ovidiu A. Pop
Technical University of Cluj-Napoca, Romania

Technical Program Chair

Tanja Braun
Fraunhofer IZM Berlin, Germany

Exhibition Chairs

Rajmond Jano
Technical University of Cluj-Napoca

Steffen Kröhnert
ESPAT-Consulting

More Information

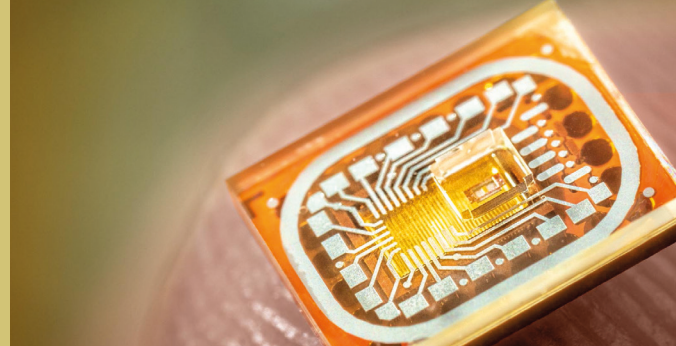
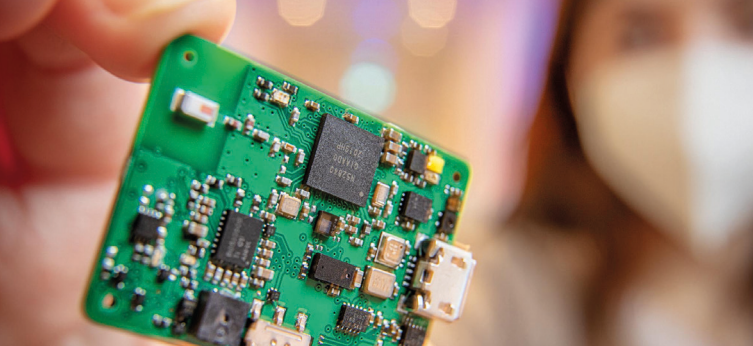
www.estc-conference.net

ESTC 2022

SEPTEMBER 13 – 16, 2022

SIBIU-HERMANNSTADT, ROMANIA





CONFERENCE TOPICS & FEES

The technical program will include oral talks, poster presentations, an exhibition, special sessions and invited keynote talks given by renowned speakers. The following topics will be covered:

- Advanced packaging
- Materials for interconnects and packaging
- Optoelectronic systems packaging
- Assembly and manufacturing technologies
- Design tools and modeling
- Power electronics system packaging
- Advanced technologies for emerging system
- Reliability and quality of electronic devices and systems
- Flexible, printed and hybrid electronics
- RF, mm-wave and THz systems packaging
- Global education for electronics

Conference fees will be as follows:

Registration fee	Early bird	Regular
Conference fee (full)	590€	690€
IEEE&IMAPS members	490€	590€
Speaker/Chair&CoChair	450€	550€
Accompanying person	245€	290€
Student fee	220€	250€

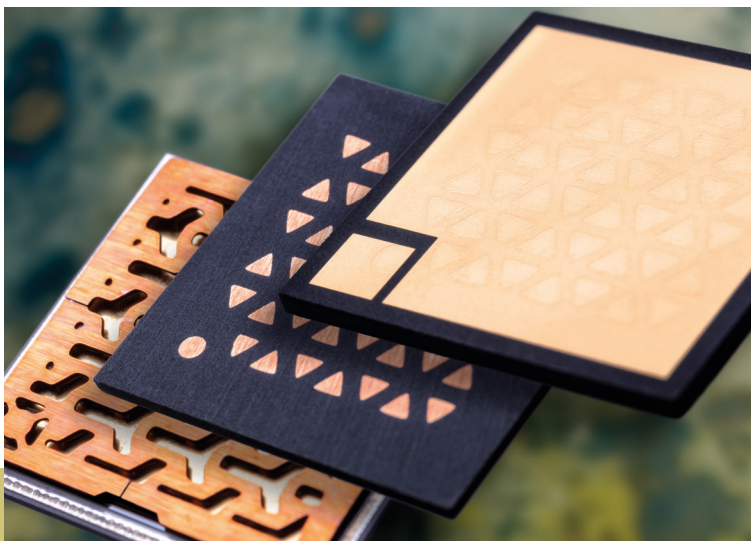
Early bird deadline: July 15, 2022.

EXHIBITOR PACKAGES

The conference provides your company or institution strong visibility and access to more than 300 engineers, managers, and decision makers from all areas of the microelectronics and system-integration industry, academics, and research institutes. These include material, equipment, software tools, design and simulation, processes and services for semiconductor assembly, interconnect, packaging, test, process control and analysis technologies as well as market research.

We offer exhibitors the following options:

Standard exhibition stand:	2,500€
Double exhibition stand:	4,800€



SPONSORING PACKAGES

There are several ways to become a supporter of the 9th ESTC. Participation for instance as a main sponsor – SILVER, GOLD, and DIAMOND Sponsorship Packages available – offers your company or institution an excellent way to significantly increase visibility and getting recognized at the event with a combination of promotional, on-site representation and content-related benefits all together in a value-priced package.

• Conference breaks sponsor:	1,500€
• Proceedings sponsor:	3,500€
• Conference bag sponsor:	4,000€
• Silver sponsor:	5,000€
• Gold sponsor:	7,000€
• Diamond sponsor:	12,000€

For more information, please contact

exhibition@estc-conference.net